

UNLIMITED INGENUITY



# DDR3 HIGH DENSITY

## 8Gb COMPONENTS & 16GB MODULES



To cope with the challenge of achieving double memory density without the necessity of two separate sets of control wires, IM developed a unique way to manufacture 8Gb DDR3 Single Chip Select components with the existing DRAM process technologies. From the application's point of view, it will see these components work like a monolithic device. IM's 8Gb Single Chip Select components are compatible with the JEDEC pinout of monolithic devices and provide the simplest path to upgrading applications using DDR3 DRAM.

**Intelligent Memory** not only offers DDR3 8Gb Single Chip Select components, but also DDR3 8Gb Two Chip Select components with the full range of DDR3 8Gb product lines. Besides components, IM introduced the very first 16GB unbuffered DIMM and SO-DIMM memory modules, based on their 8Gb Single Chip Select components. The modules follow the 2 ranks JEDEC specification.



For more information or to request samples, please visit us at [www.intelligentmemory.com](http://www.intelligentmemory.com)

You may also contact our sales team directly at [sales@intelligentmemory.com](mailto:sales@intelligentmemory.com)

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# DDR3 HIGH DENSITY 8GB COMPONENTS & 16GB MODULES

## Key Features

- Longevity for more than 5 years & long-term support
- Commercial and Industrial temperature grades available
- **Components**
  - Available in x4, x8, and x16 organizations with 1-CS and 2-CS
  - BGA components ensure long-term reliability
  - Speeds up to DDR3L-2133
- **Modules**
  - 16GB UDIMM & SO-DIMM modules (ECC optional)
  - Speeds up to PC3-14900
  - “Plug-and-Play” modules compatible with JEDEC standards

## Applications

- Aerospace and Defense
- Automation Systems
- Data Storage Systems
- Embedded Systems
- Energy and Utilities
- Industrial Automation
- Industrial PCs
- Manufacturing Control Systems
- Medical Devices & Imaging
- Military and Aerospace Systems
- Networking Equipment
- Telecommunications
- Test and Measurement Equipment

### Product List DDR3 8Gb 1-CS Components

Part No.	Density	Org.	Voltage	Package	Speed	Temperature
IM8G08D3FFBG-(125/107/093)(I)	8Gb 1-CS	1Gx8	1.35V (1.5V)	FBGA 78	1600/1866/2133	Comm./Ind.
IM8G16D3FFBG-(125/107/093)(I)	8Gb 1-CS	512Mx16	1.35V (1.5V)	FBGA 96	1600/1866/2133	Comm./Ind.

### Product List DDR3 8Gb 2-CS Components

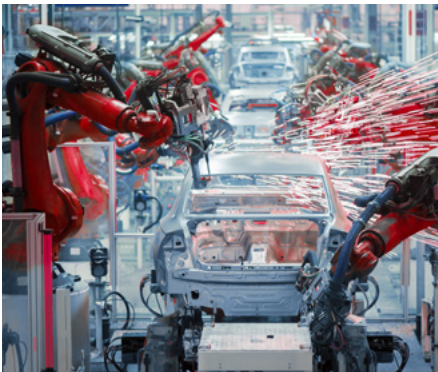
Part No.	Density	Org.	Voltage	Package	Speed	Temperature
IM8G04D3FFDG-(125/107/093)(I)	8Gb 2-CS	2Gx4	1.35V (1.5V)	FBGA 78	1600/1866/2133	Comm./Ind.
IM8G08D3FFDG-(125/107/093)(I)	8Gb 2-CS	1Gx8	1.35V (1.5V)	FBGA 78	1600/1866/2133	Comm./Ind.
IM8G16D3FFDG-(125/107/093)(I)	8Gb 2-CS	512Mx16	1.35V (1.5V)	FBGA 96	1600/1866/2133	Comm./Ind.

### Product List DDR3 16GB SO-DIMM Memory Modules

Part No.	Density	Org.	Voltage	Package	Speed	Temperature
IMM2G64D3LSOD8AG-F(125/107)(I)	16GB SO-DIMM	2Gx64	1.35V (1.5V)	204 Pin	1600/1866	Comm./Ind.
IMM2G72D3LSOD8AG-F(125/107)(I)	16GB ECC SO-DIMM	2Gx72	1.35V (1.5V)	204 Pin	1600/1866	Comm./Ind.

### Product List DDR3 16GB UDIMM Memory Modules

Part No.	Density	Org.	Voltage	Package	Speed	Temperature
IMM2G64D3LDUD8AG-F(125/107)(I)	16GB UDIMM	2Gx64	1.35V (1.5V)	204 Pin	1600/1866	Comm./Ind.
IMM2G72D3LDUD8AG-F(125/107)(I)	16GB ECC UDIMM	2Gx72	1.35V (1.5V)	204 Pin	1600/1866	Comm./Ind.



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